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Reference to:  
Application No.: 10/765,346  
Filing date: 1/26/2004  
Art unit: 2813  
Applicants: Hui Peng  
Title: New Flip Chip Assemblies and Lamps of High Power GaN LEDs, Wafer  
Level Flip Chip Package Process, and Method of Fabricating the Same  
Examiner/Art Unit Jennifer M. Dolan/2813

Fremont, CA, Nov. 17, 2005

**AMENDMENT A**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir/Ms.:

This letter responses to the Office Action Summary mailed to applicants on Oct. 31, 2005.

Please amend the above patent application as the following.

Applicants' Oct. 7, 2005 letter was responding to the Office Action Summary mailed to applicants on July 27, 2005, therefore, the response was within 3 month, not extended.

**TITLE:** There is no amendment to the title.

**SPECIFICATION:** There is no amendment to the specification.

**CLAIMS:** Amendment to the claims of the above patent application begin on page 2 of  
this amendment.

**DRAWINGS:** There is no amendment to the drawings.